100 V, 3.0 A, Low V_{CE(sat)} **NPN Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	100	Vdc
Collector-Base Voltage	V_{CBO}	140	Vdc
Emitter-Base Voltage	V_{EBO}	7.0	Vdc
Collector Current - Continuous	I _C	2.0	Α
Collector Current - Peak	I _{CM}	3.0	Α

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 1)	490 3.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{0JA} (Note 1)	255	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 2)	710 4.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	176	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	−55 to +150	°C

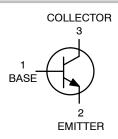
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



ON Semiconductor®

www.onsemi.com

100 VOLTS, 3.0 AMPS NPN LOW V_{CE(sat)} TRANSISTOR





MARKING DIAGRAM



VT = Specific Device Code

= Date Code*

= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS1C201LT1G, NSV1C201LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{1.} FR-4 @ 100 mm², 1 oz. copper traces. 2. FR-4 @ 500 mm², 1 oz. copper traces.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage ($I_C = 10 \text{ mAdc}, I_B = 0$)	V _{(BR)CEO}	100			Vdc
Collector – Base Breakdown Voltage ($I_C = 0.1 \text{ mAdc}, I_E = 0$)	V _{(BR)CBO}	140			Vdc
Emitter – Base Breakdown Voltage ($I_{\rm E}=0.1$ mAdc, $I_{\rm C}=0$)	V _{(BR)EBO}	7.0			Vdc
Collector Cutoff Current (V _{CB} = 140 Vdc, I _E = 0)	Ісво			100	nAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}			50	nAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3) ($I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$) ($I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$)	h _{FE}	150 120 80 40	240	360	
Collector – Emitter Saturation Voltage (Note 3) ($I_C = 0.1 \text{ A}, I_B = 0.01 \text{ A}$) ($I_C = 0.5 \text{ A}, I_B = 0.05 \text{ A}$) ($I_C = 1.0 \text{ A}, I_B = 0.100 \text{ A}$) ($I_C = 2.0 \text{ A}, I_B = 0.200 \text{ A}$)	V _{CE(sat)}			0.030 0.060 0.090 0.150	V
Base – Emitter Saturation Voltage (Note 3) (I _C = 1.0 A, I _B = 0.100 A)	V _{BE(sat)}			0.950	V
Base – Emitter Turn–on Voltage (Note 3) (I _C = 1.0 A, V _{CE} = 2.0 V)	V _{BE(on)}			0.850	V
Cutoff Frequency (I _C = 100 mA, V _{CE} = 5.0 V, f = 100 MHz)	f _T		110		MHz
Input Capacitance (V _{EB} = 2.0 V, f = 1.0 MHz)	Cibo		230		pF
Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	Cobo		14		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

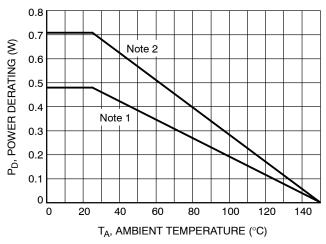


Figure 1. Power Derating

TYPICAL CHARACTERISTICS

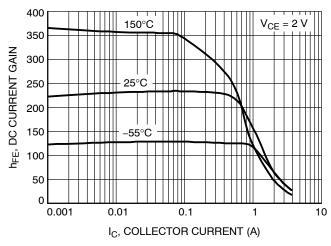
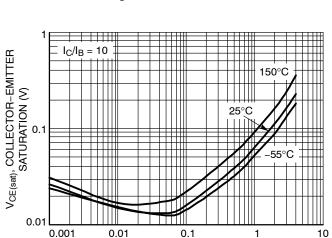


Figure 2. DC Current Gain



 $\label{eq:lc} I_{C}, \, \text{COLLECTOR} \, \, \text{CURRENT} \, \, \text{(A)}$ Figure 4. Collector–Emitter Saturation Voltage

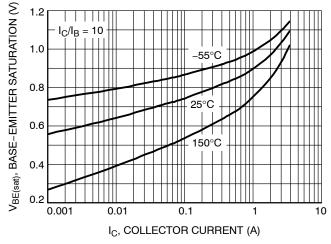


Figure 6. Base-Emitter Saturation Voltage

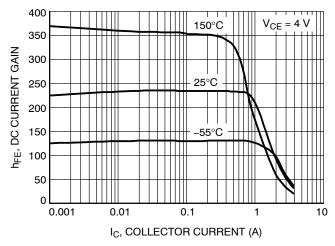


Figure 3. DC Current Gain

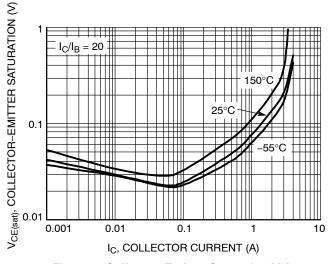


Figure 5. Collector-Emitter Saturation Voltage

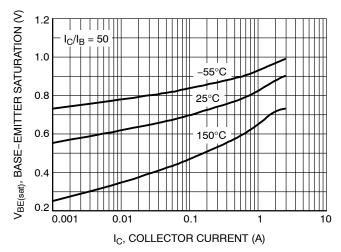
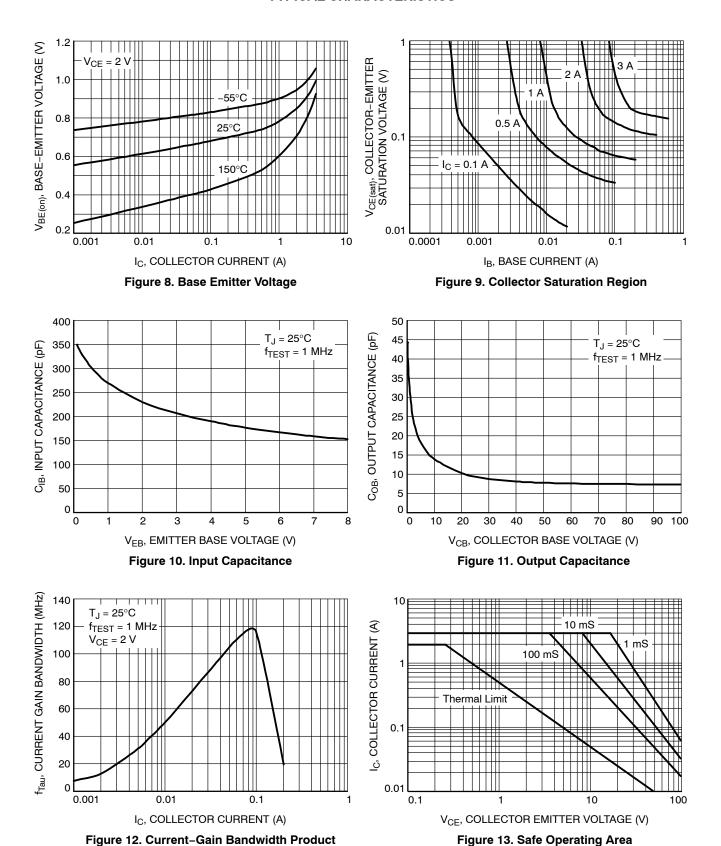


Figure 7. Base-Emitter Saturation Voltage

TYPICAL CHARACTERISTICS



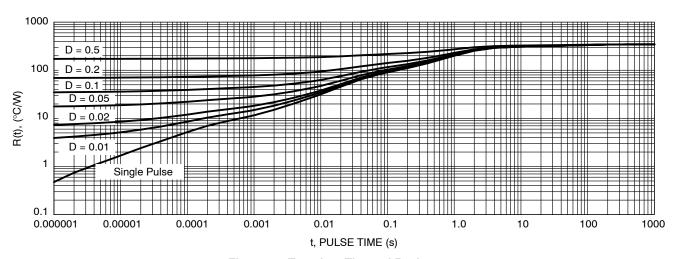


Figure 14. Transient Thermal Resistnce

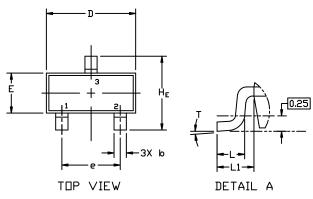


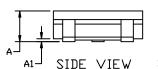


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NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



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STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: N PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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